

25. (New) Support apparatus for an installation of semiconductor processing equipment having a bottom outline and a plurality of load-bearing mounting feet disposed along the equipment's bottom outline comprising:

a plurality of support legs; and

a frame disposed on the plurality of support legs, the frame having a frame outline which substantially duplicates the bottom outline of the semiconductor processing equipment, the frame being configured to support the installation of semiconductor processing equipment and to provide one or more facilities connection locations that are pre-aligned to one or more facilities connection points of the semiconductor processing equipment.

26. (New) The support apparatus of claim 25 wherein the plurality of support legs include at least one support leg aligned to each one of the plurality of load-bearing mounting feet.

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#### REMARKS

Claims 1-13 and 21-26 are now in this application, claim 20 having been canceled and claims 23-26 having been added in this paper. Claims 1-13 and 21-22 stand rejected and are now presented for reconsideration in view of the foregoing amendments and the following remarks.

Applicants appreciate having had an opportunity to discuss the present application with the Examiner during a telephone interview on February 11, 2003. During the telephone interview, Applicants' undersigned attorney, Brian M. Dugan, discussed the currently pending claims in light of the Admitted Prior Art (APA) of FIGS. 1 and 2 of Applicants'

specification and U.S. Patent No. 4,243,197 (Wright). Applicants' undersigned attorney stated that the APA of FIG. 2 is a proposed industry standard, and as such, teaches away from any modification of the proposed SEMI pedestal. That is, any modification of the APA of FIG. 2 in light of the APA of FIG. 1, the Wright reference or any other reference, would run contrary to the purpose of the APA of FIG. 2 to provide an industry standard. No specific agreement was reached. The Examiner suggested Applicants review U.S. Patent No. 6,312,525 (Bright et al.) as this reference may be relied upon during a subsequent office action.

#### Examiner's Rejections

Applicants respectfully traverse the Examiner's rejection of claims 1-5, 7-11 and 21-22 as being unpatentable over the APA of FIG. 2 in view of the APA of FIG. 1 and further in view of Wright. With regard to independent claim 1, as stated above, the APA of FIG. 2 is a proposed industry standard and any modification of the APA of FIG. 2 in light of the APA of FIG. 1, the Wright reference or any other cited reference, would run contrary to the purpose and teachings of the APA of FIG. 2 (which is to provide an industry standard). For at least this reason, Applicants respectfully submit that claim 1 and claims 2-5 and 7-11 which depend therefrom are allowable over the prior art of record. Dependent claims 6, 12 and 13 are similarly submitted as allowable.

Note that claim 20 has been cancelled and the limitation of claim 1 that the plurality of support legs include "at least one support leg aligned to each one of the plurality of load-bearing mounting feet" of the semiconductor processing equipment has been removed from claim 1 and

included in new claim 23 which depends from claim 1. The same limitation has been removed from claim 21 and included in new claim 24 which depends from claim 21.

Regarding independent claim 21, Applicants have amended claim 21 to include the limitation that the frame is configured to provide one or more facilities connection locations that are pre-aligned to one or more facilities connection points of the semiconductor processing equipment to be supported by the frame. Support for this feature may be found, for example, on page 7, lines 30-36 of Applicants' specification. Applicants respectfully submit that the prior art of record fails to disclose, teach or otherwise suggest such a feature; and that claim 21 and claim 22 which depends therefrom are allowable.

New claim 25 is similar to claim 1, but includes the above limitation that the frame is configured to provide one or more facilities connection locations that are pre-aligned to one or more facilities connection points of the semiconductor processing equipment to be supported by the frame. Accordingly, new claim 25 is submitted as patentable on at least the same basis as claims 1 and 21. New claim 26 is similar to new claims 23 and 24, but depends from claim 25.

#### Newly Cited References

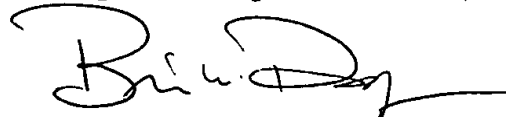
In response to the Examiner's suggestion, Applicants enclose herewith an information disclosure statement that cites U.S. Patent No. 6,312,525 (Bright et al.) and corresponding WIPO published application WO9903133A1. Applicants respectfully submit that these references merely show exemplary semiconductor wafer fabrication equipment (albeit semiconductor wafer fabrication

equipment that has a "modular architecture") that could be supported by Applicants' claimed support apparatus. Such wafer fabrication equipment would have to be supported by some support apparatus during operation (e.g., Applicants' claimed invention, the APA of FIG. 1, the APA of FIG. 2, etc.). Accordingly, Applicants respectfully submit that the claims of the present application are allowable over these references.

In view of the foregoing, all pending claims are believed to be allowable, and passage to issue is respectfully required.

A separate Request for a Three-Month Extension of Time and the requisite fee are enclosed herewith. Applicants do not believe any other fees are due regarding this amendment. If any additional fees are required, however, please charge Deposit Account No. 04-1696. Applicants encourage the Examiner to telephone Applicants' attorney to discuss the amendment should any issues remain.

Respectfully submitted,

A handwritten signature in black ink, appearing to read "Brian M. Dugan", with a long horizontal flourish extending to the right.

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Dated: February 20, 2003  
Tarrytown, New York

VERSION MARKED TO SHOW CHANGES

In the Claims:

Please cancel claim 20 without prejudice.

Please amend claims 1 and 21 to read as follows:

1. (Twice Amended) Support apparatus for an installation of semiconductor processing equipment having a bottom outline and a plurality of load-bearing mounting feet disposed along the equipment's bottom outline comprising:

a plurality of support legs [including at least one support leg aligned to each one of the plurality of load-bearing mounting feet]; and

a frame disposed on the plurality of support legs, the frame having a frame outline which substantially duplicates the bottom outline of the semiconductor processing equipment, the frame being configured to support the installation of semiconductor processing equipment.

21. (Amended) Support apparatus for an installation of semiconductor processing equipment having a plurality of load-bearing mounting feet at a bottom of the semiconductor processing equipment comprising:

a plurality of support legs [including at least one support leg aligned to each one of the plurality of load-bearing feet]; and

a frame disposed on the plurality of support legs, the frame being configured to support the installation of semiconductor processing equipment and to provide one or more facilities connection locations that are pre-aligned to one or more facilities connection points of the semiconductor processing equipment.